

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re The Application of: )  
David Chong Sook Lim et al. )

Serial No.: 10/664,982 )

Examiner: Leonardo Andujar

Filed: September 17, 2003 )

Art Unit: 2826

For: PACKAGING SYSTEM FOR )  
DIE-UP CONNECTION OF A )  
DIE-DOWN ORIENTED INTE- )  
GRATED CIRCUIT )

Cesari and McKenna, LLP  
88 Black Falcon Avenue  
Boston, MA 02210  
May 22, 2007

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

**AMENDMENT**

In response to the Office action dated 2/28/2007, please consider the following.